

Packaging of components for automatic handling - Part  
3: Packaging of surface mount components on  
continuous tapes

## EESTI STANDARDI EESSÕNA

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See Eesti standard EVS-EN IEC 60286-3:2019 sisaldab Euroopa standardi EN IEC 60286-3:2019 ingliskeelset teksti.	This Estonian standard EVS-EN IEC 60286-3:2019 consists of the English text of the European standard EN IEC 60286-3:2019.
Standard on jõustunud sellekohase teate avaldamisega EVS Teatajas.	This standard has been endorsed with a notification published in the official bulletin of the Estonian Centre for Standardisation.
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English Version

**Packaging of components for automatic handling - Part 3:  
Packaging of surface mount components on continuous tapes  
(IEC 60286-3:2019)**

Emballage de composants pour opérations automatisées -  
Partie 3: Emballage des composants pour montage en  
surface en bandes continues  
(IEC 60286-3:2019)

Gurtung und Magazinierung von Bauelementen für  
automatische Verarbeitung - Teil 3: Gurtung von  
oberflächenmontierbaren Bauelementen auf Endlosgurten  
(IEC 60286-3:2019)

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**CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels**

## European foreword

The text of document 40/2643/FDIS, future edition 6 of IEC 60286-3, prepared by IEC/TC 40 "Capacitors and resistors for electronic equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60286-3:2019.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2019-11-20
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2022-02-20

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61340-5-1	NOTE Harmonized as EN 61340-5-1
IEC/TR 61340-5-2	NOTE Harmonized as CLC/TR 61340-5-2
IEC/TR 62258-3	NOTE Harmonized as CLC/TR 62258-3
ISO 11469	NOTE Harmonized as EN ISO 11469

## Annex ZA

(normative)

### Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191-2	-	Mechanical standardization of semiconductor devices -- Part 2: Dimensions		-

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –****Part 3: Packaging of surface mount components  
on continuous tapes****FOREWORD**

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International Standard IEC 60286-3 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment.

This sixth edition cancels and replaces the fifth edition published in 2013. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) addition of a table of the classification to symbols concerning tape, reel and common symbols;
- b) additions of a figure of example of polarity and orientation and a figure of example of dot seal;
- c) revision of requirements for camber;

d) addition of a definition of design value with regard to tilt.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
40/2643/FDIS	40/2649/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60286 series, published under the general title *Packaging of components for automatic handling*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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## INTRODUCTION

Tape packaging meets the requirements of automatic component placement machines and also covers the use of tape packaging for components and singulated dies for test purposes and other operations.

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